

Nch 500V 13A Power MOSFET

V_{DSS}	500V
$R_{DS(on)}(Max.)$	0.52Ω
I _D	-13A
P_D	40W

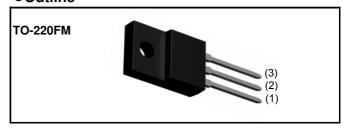
Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Gate-source voltage (V_{GSS}) guaranteed to be $\pm 30V$.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.
- 6) Pb-free lead plating; RoHS compliant

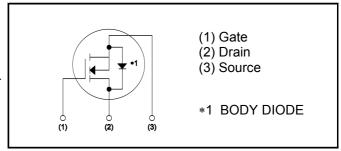
Application

Switching Power Supply

Outline



•Inner circuit



Packaging specifications

		
	Packaging	Bulk
	Reel size (mm)	-
Typo	Tape width (mm)	-
Туре	Basic ordering unit (pcs)	500
	Taping code	-
	Marking	ZDX130N50

● Absolute maximum ratings(T_a = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	500	V
Continuous drain current $T_c = 25^{\circ}C$		I _D *1	±13	Α
Pulsed drain current		I _{D,pulse} *2	±39	А
Gate - Source voltage		V_{GSS}	±30	V
Power dissipation (T _c = 25°C)		P _D	40	W
Junction temperature		T _j	150	°C
Range of storage temperature		T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
raiametei	Зуппоп	Min.	Тур.	Max.	Offic
Thermal resistance, junction - ambient	R_{thJA}	-	-	3.125	°C/W

• Electrical characteristics ($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit	
r ai ai nietei	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	500	ı	-	V	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 500V, V _{GS} = 0V	1		100	μА	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	ı	1	±100	nA	
Gate threshold voltage	V _{GS (th)}	V_{DS} = 10V, I_D = 1mA	2.5	ı	4.5	V	
Static drain - source on - state resistance	R _{DS(on)} *3	$V_{GS} = 10V, I_D = 6.5A$	-	0.4	0.52	Ω	

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Transconductance	g _{fs} *3	$V_{DS} = 10V, I_{D} = 6A$	2.0	8.5	-	S
Input capacitance	C _{iss}	V _{GS} = 0V	-	2180	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	200	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	1	60	-	
Turn - on delay time	$t_{d(on)}^{*3}$	$V_{DD} \simeq 250V, V_{GS} = 10V$	ı	30	-	
Rise time	t _r *3	I _D = 5A	ı	25	-	ns
Turn - off delay time	$t_{d(off)}^{*3}$	$R_L = 50\Omega$	-	43	-	115
Fall time	t _f *3	$R_G = 10\Omega$	-	15	-	

•Gate Charge characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*3}	$V_{DD} \simeq 250V$	-	40	-	
Gate - Source charge	Q _{gs} *3	I _D = 5A	-	11.5	-	nC
Gate - Drain charge	Q _{gd} *3	V _{GS} = 10V	-	12.5	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 250V$, $I_D = 5A$	-	5.5	-	V

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} Pulsed

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai ii etei	Symbol Conditions -		Min.	Тур.	Max.	Offic
Inverse diode continuous, forward current	l _s *1	T _c = 25°C	ı	-	13	А
Inverse diode direct current, pulsed	I _{SM} *2	11c - 25 0	•	-	39	Α
Forward voltage	V _{SD} *3	V _{GS} = 0V, I _S = 13A	-	-	1.7	V

Power Dissipation: P_D/P_D max. [%]

•Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

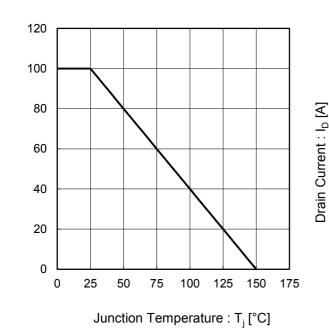
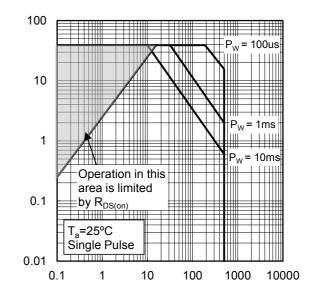
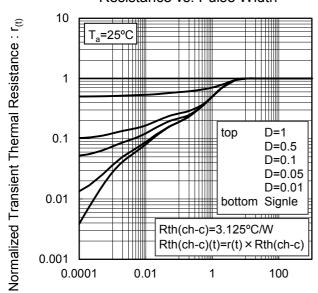


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

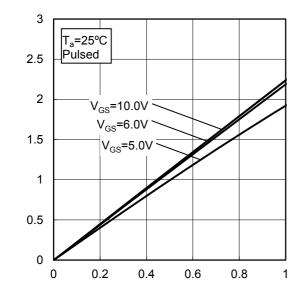


Pulse Width: Pw[s]

Drain Current : I_D [A]

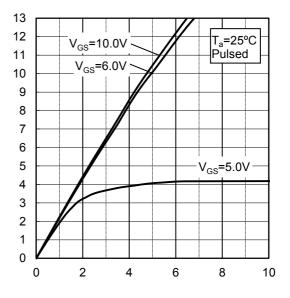
• Electrical characteristic curves

Fig.4 Typical Output Characteristics(I)



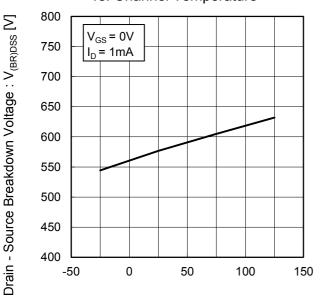
Drain - Source Voltage : V_{DS} [V]

Fig.5 Typical Output Characteristics(II)



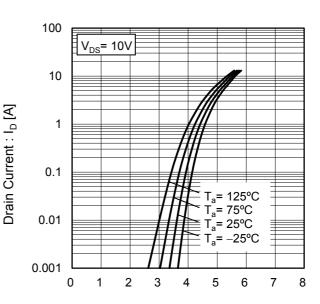
Drain - Source Voltage : V_{DS} [V]

Fig.6 Breakdown Voltage vs. Channel Temperature



Junction Temperature : T_i [°C]

Fig.7 Typical Transfer Characteristics



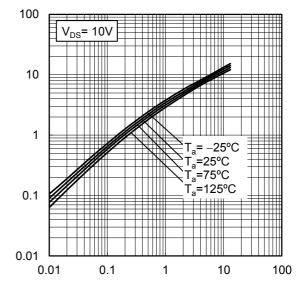
Gate - Source Voltage : V_{GS} [V]

Drain Current: I_D [A]

• Electrical characteristic curves

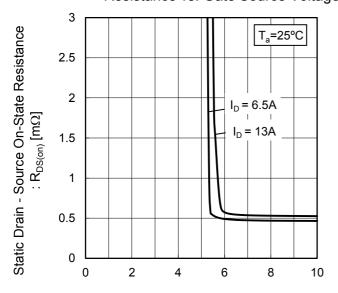
Fig.8 Gate Threshold Voltage vs. Channel Temperature 5.0 $V_{DS} = 10V$ $I_D = 1 \text{mA}$ Gate Threshold Voltage: V_{GS(th)} [V] 4.0 3.0 2.0 1.0 0.0 -50 -25 0 25 50 75 100 125 150 Junction Temperature : T_i [°C]

Fig.9 Transconductance vs. Drain Current



Drain Current : I_D [A]

Fig.10 Static Drain - Source On - State Resistance vs. Gate Source Voltage

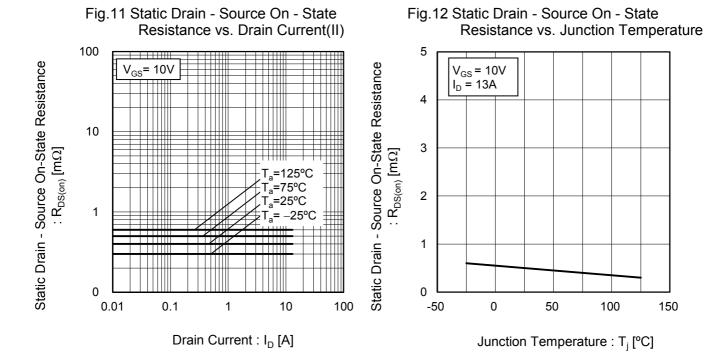


Gate - Source Voltage : V_{GS} [V]

Transconductance : g_{fs} [S]

150

• Electrical characteristic curves



• Electrical characteristic curves

Fig.13 Typical Capacitance vs. Drain - Source Voltage

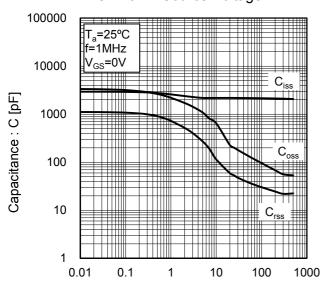
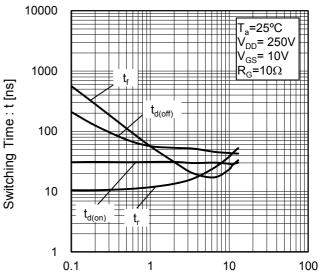


Fig.14 Switching Characteristics



Drain - Source Voltage : V_{DS} [V] Drain Current : I_D [A]

Fig.15 Dynamic Input Characteristics

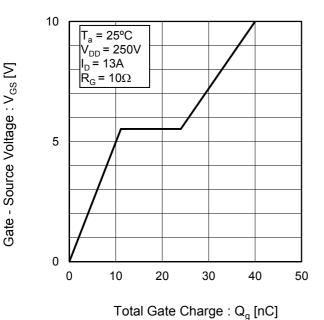
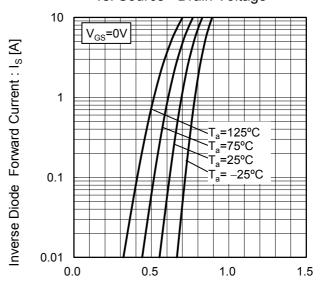


Fig.16 Inverse Diode Forward Current vs. Source - Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

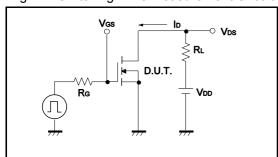


Fig.2-1 Gate Charge Measurement Circuit

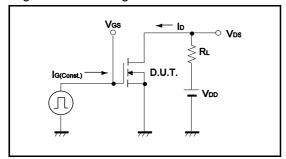


Fig.1-2 Switching Waveforms

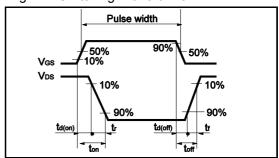
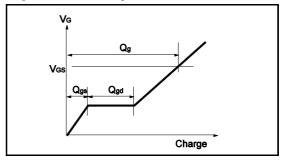
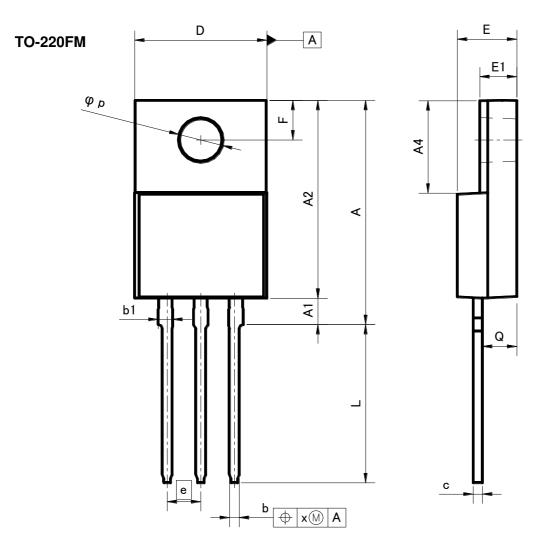


Fig.2-2 Gate Charge Waveform



● **Dimensions** (Unit: mm)



DIM MIL		ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.85	0.028	0.033
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.39	0.406
Е	4.40	4.80	0.173	0.189
е	2.54		0.	10
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.11	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
х	_	0.381	_	0.015

Dimension in mm/inches

Notice

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JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	СГУССШ
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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